



X-65-130U

Shin-Etsu Silicones of America, Inc.
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Product Description

Shin-Etsu X-65-130 U is a black semi-conductive silicone compound with typical volume resistivity of 0.5 ohm-cm for molding and extruding.

Product Features

- Good processability.
- Lower than average volume resistivity.
- Can be catalyzed with both peroxide and addition cure catalysts.

Typical Applications

- EMI gaskets.
- Key pads.
- Medical motor stimulant pads.

Typical Properties

Type of HCR	Electronically Conductive
Cure Agent	DBPH
Cure Agent B	DBPH-50
Durometer	70
CA-B Durometer	71
Tensile Strength (psi)	695
CA-B Tensile Strength (psi)	665
Elongation (%)	130
CA-B Elongation (%)	130
Specific Gravity	1.28
CA-B Specific Gravity	1.28
Tear Die B (ppi)	70
CA-B Tear Die B (ppi)	75
Compression Set (%)	20
CA-B Compression Set (%)	15
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	180
Comp. Set Temp. (°F)	356
Press Cure/Post Cure	Press

Note: Values are not for specification purposes.

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